



Stitch and Dot Optimized EVA Packaging Hot Melt

Use up to 50% less adhesive

superDOT E100 is a premium EVA hot melt adhesive formulated for applications using hot melt stitching and dotting to reduce adhesive consumption up to 50%. It offers fast tack and excellent adhesion to cardboard, corrugated and some coated stocks. superDOT E100 also has very good cold and hot temperature resistance.

TYPICAL PROPERTIES

Application Temperature Range	325-360 °F
Viscosity @ 350°F	1,100 cps
Heat Stability	Excellent
Open Time	Short
Softening Point	238°F
Product Form	Chips or Pellets

FEATURES

- Very Fast Hot Tack
- Excellent Heat Resistance
- Excellent Cold Resistance
- Bonds to Glass

COMMON APPLICATIONS

- High Speed Packaging
- Semi-Automated Packaging
- Food Packaging
- Tray Forming

BONDS TO

- Cardboard
- Corrugated
- Paper
- Coated Stocks
- Glass

IMPORTANT NOTICE TO CUSTOMER

The information herein is general information designed to assist customers in determining whether our products are suitable for their applications. Our products are intended for sale to industrial and commercial customers. We require customers to inspect and test our products before use to and to satisfy themselves as to contents and suitability for their specific applications. We warrant that our products will meet our written specifications. Nothing herein shall constitute any other warranty express or implied, including any warranty of merchantability or fitness for a particular purpose, nor is any protection from any law or patent to be inferred. All patent rights are reserved. The exclusive remedy for all proven claims is limited to replacement of our materials and in no event shall we be liable for special, incidental or consequential damages.